

*CLAIM AMENDMENTS*

Claims 1-13 (Cancelled).

14. (Currently Amended) A method of chemical mechanical polishing ~~of an object~~ comprising:

supplying a slurry including polishing particles to a polishing apparatus including a polisher and ~~the~~ an object to be polished;

measuring particle information, including at least one of dispersion of the polishing particles and distribution of particle sizes of the polishing particles, of the slurry ~~being that is directly~~ supplied to ~~and directly used in polishing of~~ the object in the polishing apparatus; and

controlling polishing speed at which the object is being polished, based on the particle information by adjusting at least one of rotation speed of the polisher, rotation speed of the object, and force applied by the polisher to the object.

Claims 15 and 16 (Cancelled).

17. (Currently Amended) The method according to claim 14 including supplying a mixture of a first slurry and a second slurry to the polishing apparatus as the slurry directly supplied to the object.

18. (Previously Presented) The method according to claim 17 including controlling mixing ratio between the first slurry and the second slurry based on the particle information.

19. (Previously Presented) The method according to claim 18, further comprising:  
detecting the polishing speed at which the object is being polished; and  
controlling the mixing ratio based on the polishing speed.

Claim 20 (Cancelled).